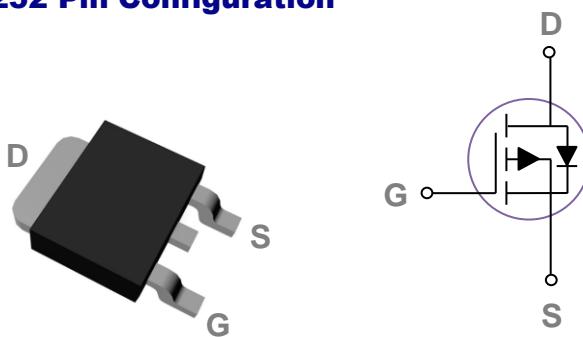


### General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO252 Pin Configuration



BVDSS	RDS(ON)	ID
-20V	8.4mΩ	-60A

### Features

- -20V, -60A,  $RDS(ON) = 8.4m\Omega @ VGS = -4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

### Applications

- Notebook
- Load Switch
- Networking
- Hand-Held Instruments

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	-60	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	-38	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	-240	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	157	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	-56	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	61	W
	Power Dissipation – Derate above $25^\circ C$	0.49	W/ $^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	2.04	$^\circ C/W$

**Electrical Characteristics ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-20	---	---	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-20\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	uA
		$V_{DS}=-16\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=125\text{ }^{\circ}\text{C}$	---	---	-10	uA
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 10\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5\text{V}$ , $I_D=-15\text{A}$	---	7	8.4	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$ , $I_D=-10\text{A}$	---	9.6	12	
		$V_{GS}=-1.8\text{V}$ , $I_D=-8\text{A}$	---	14	18	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D = -250\mu\text{A}$	-0.3	-0.6	-1	V
$g_{fs}$	Forward Transconductance	$V_{DS}=-10\text{V}$ , $I_S=-3\text{A}$	---	15	---	S

**Dynamic and switching Characteristics**

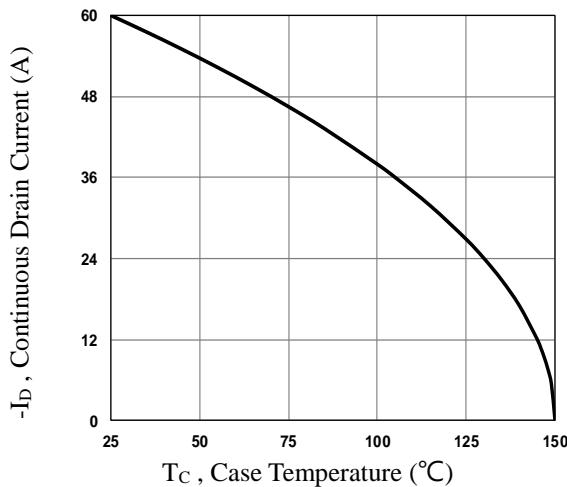
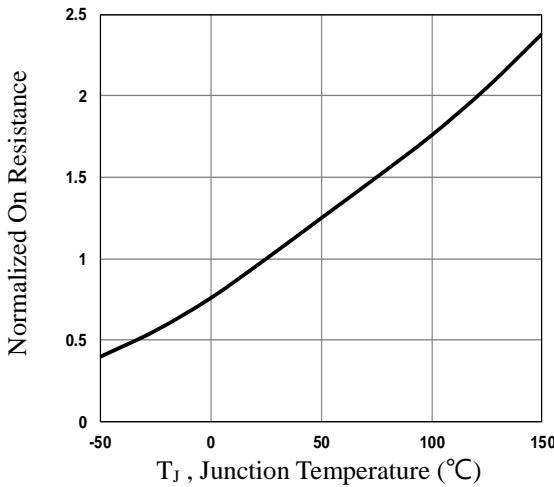
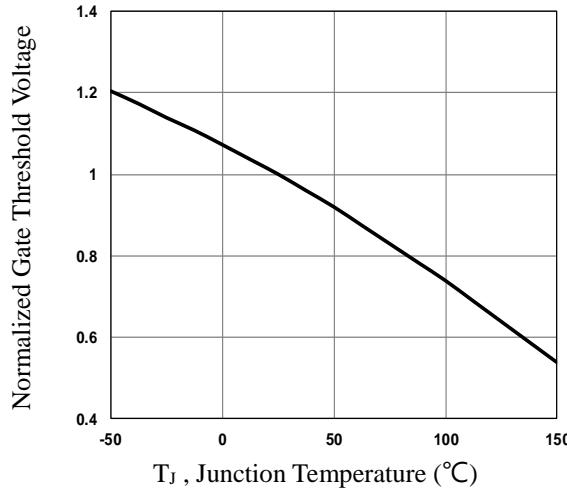
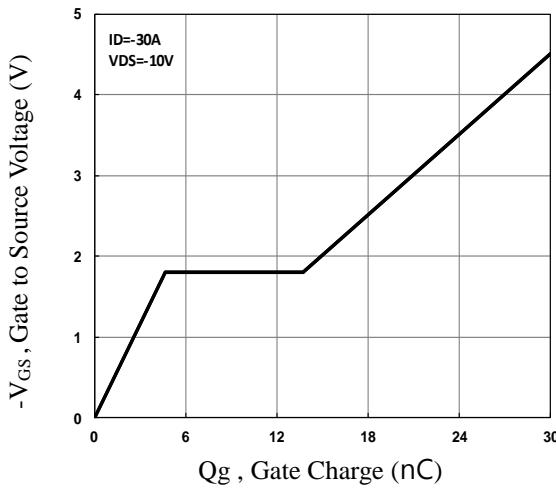
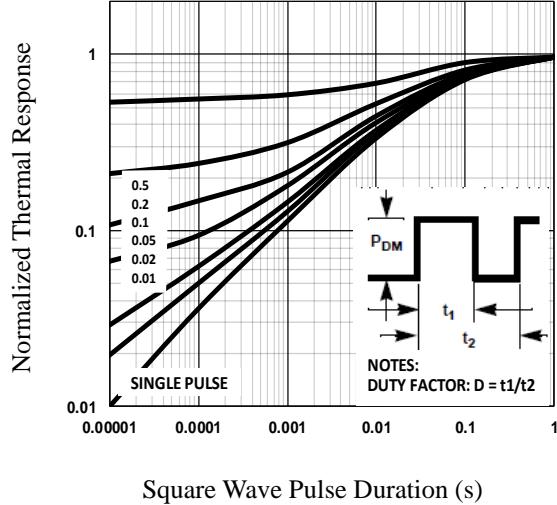
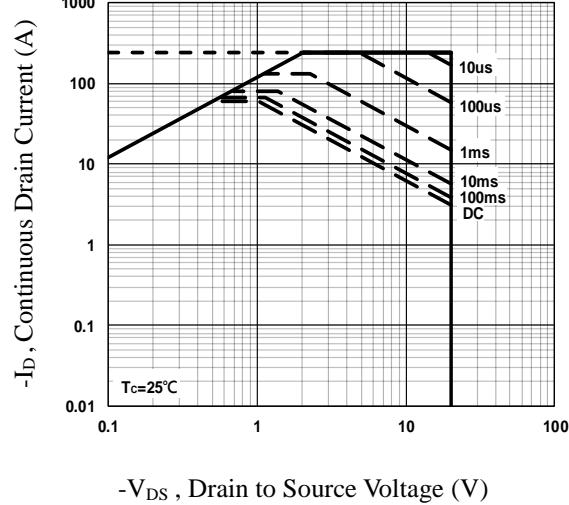
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=-10\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-30\text{A}$	---	30	45	$\text{nC}$
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		---	4.7	7.1	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		---	9	13.5	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=-10\text{V}$ , $V_{GS}=-4.5\text{V}$ , $R_G=6\Omega$ $I_D=-30\text{A}$	---	15	23	$\text{nS}$
$T_r$	Rise Time <sup>3, 4</sup>		---	20	30	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		---	30	55	
$T_f$	Fall Time <sup>3, 4</sup>		---	25	38	
$C_{iss}$	Input Capacitance	$V_{DS}=-10\text{V}$ , $V_{GS}=0\text{V}$ , $F=1\text{MHz}$	---	3300	5000	$\text{pF}$
$C_{oss}$	Output Capacitance		---	420	630	
$C_{rss}$	Reverse Transfer Capacitance		---	370	560	
$R_g$	Gate resistance	$V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $F=1\text{MHz}$	---	5	---	$\Omega$

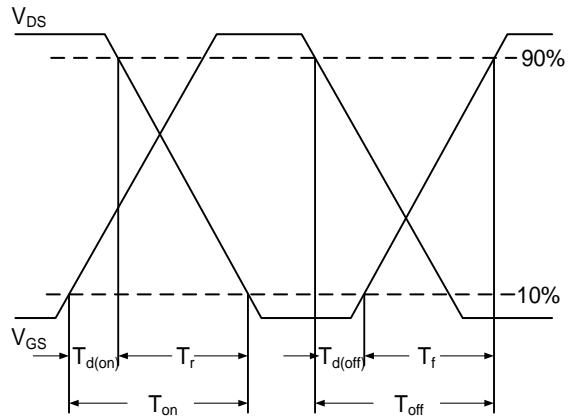
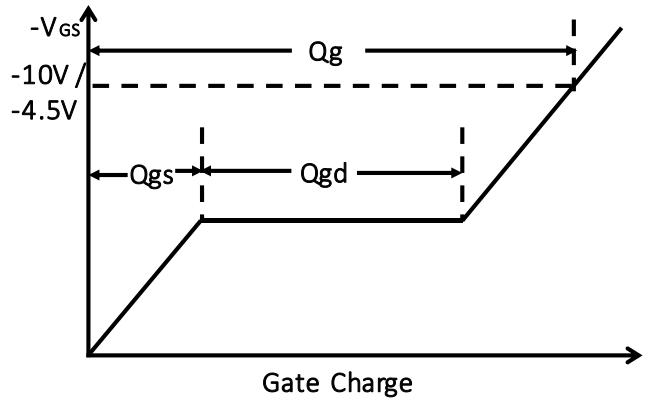
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	-60	A
$I_{SM}$	Pulsed Source Current		---	---	-120	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=-1\text{A}$ , $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	V

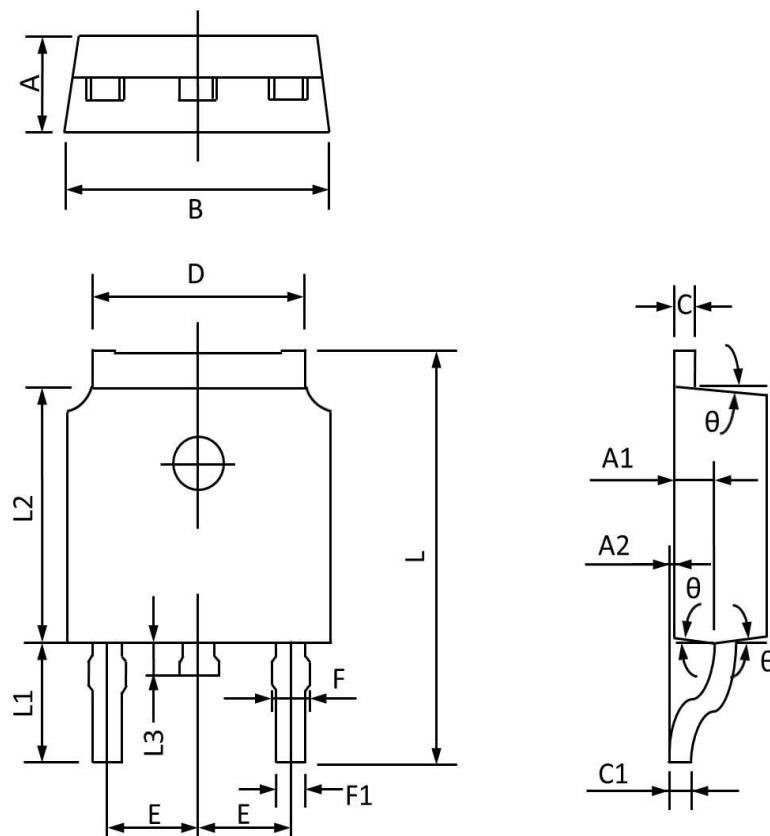
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=-25\text{V}$ ,  $V_{GS}=-10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=-56\text{A}$ , Starting  $T_J=25\text{ }^{\circ}\text{C}$
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. T<sub>c</sub>**

**Fig.2 Normalized RD<sub>SON</sub> vs. T<sub>J</sub>**

**Fig.3 Normalized V<sub>th</sub> vs. T<sub>J</sub>**

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Impedance**

**Fig.6 Maximum Safe Operation Area**


**Fig.7** Switching Time Waveform

**Fig.8** Gate Charge Waveform

## TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.450	2.150	0.096	0.085
A1	1.200	0.910	0.047	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.300	0.268	0.248
C	0.580	0.350	0.023	0.014
C1	0.550	0.380	0.022	0.015
D	5.500	5.100	0.217	0.201
E	2.390	2.000	0.094	0.079
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.300	0.244	0.209
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°